



CP 1826

#6

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: OH ET AL. DOCKET NO.: WK2K1070
SERIAL NO: 10/015,374 EXAMINER: WILLIAMS
FILED: 12/12/2001 ART UNIT: 2826
TITLE: STACKING STRUCTURE OF SEMICONDUCTOR CHIPS AND
SEMICONDUCTOR PACKAGE USING IT.

Assistant Commissioner Weiss & Moy, P.C.
for Patents 4204 North Brown Avenue
Washington, D.C. 20231 Scottsdale, Arizona 85251-3989

October 24, 2002

I hereby certify that on the 24th day of October, 2002,
this correspondence is being deposited with the U.S.
Postal Service as first class mail in an envelope
addressed to: Assistant Commissioner for Patents,
Washington, D.C. 20231.



Jeffrey D. Moy

Dear Sir:

AMENDMENT LETTER

This is in response to the Office Action dated September 27,
2002 in regards to the above identified patent application. Please
amend the subject patent application as follows: